

## Features

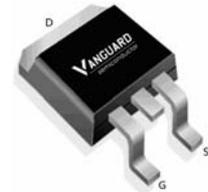
- P-Channel, -5V Logic level Control
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=-4.5\text{ V}$
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

$V_{DS}$	-100	V
$R_{DS(on),TYP}@ V_{GS}=-10\text{ V}$	25	m $\Omega$
$R_{DS(on),TYP}@ V_{GS}=-4.5\text{ V}$	28	m $\Omega$
$I_D$	-55	A



Part ID	Package Type	Marking	Tape and reel information
VSM030P10MS	TO-263	030P10M	800pcs/Reel

### TO-263



Drain Pin2



Source Pin3

## Absolute Maximum Ratings

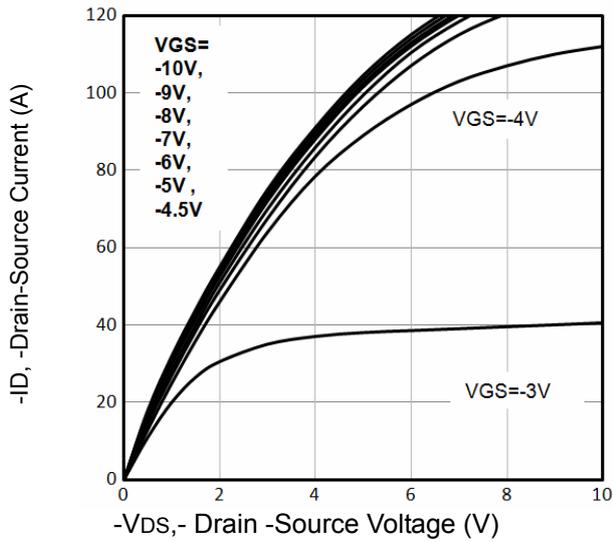
Symbol	Parameter	Rating	Unit	
<b>Common Ratings (Tc=25°C Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-100	V	
$T_J$	Maximum Junction Temperature	175	°C	
$T_{STG}$	Storage Temperature Range	-55 to 175	°C	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	-55	A
<b>Mounted on Large Heat Sink</b>				
$I_{DM}$	Pulse Drain Current Tested ①	$T_C=25^\circ\text{C}$	-180	A
$I_D$	Continuous Drain current@ $V_{GS}=10\text{V}$	$T_C=25^\circ\text{C}$	-55	A
		$T_C=100^\circ\text{C}$	-35	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	150	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.0	°C/W	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient( $t_s < 10\text{s}$ )	40	°C/W	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed ②	56	mJ	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-100	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(Tc=25°C)	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current(Tc=125°C)	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	--	--	-10	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-1.6	-2.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-25A	--	25	30	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	--	28	35	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, f=1MHz	--	7270	--	pF
C <sub>oss</sub>	Output Capacitance		--	315	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	205	--	pF
Q <sub>g</sub>	Gate Resistance	f=1MHz		13.5		Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-50V, I <sub>D</sub> =-20A, V <sub>GS</sub> =-4.5V	--	83	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	15	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	36	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-50V, I <sub>D</sub> =-20A, R <sub>G</sub> =6.8Ω, V <sub>GS</sub> =-10V	--	18	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	60	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	160	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	105	--	nS
<b>Source- Drain Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
I <sub>SD</sub>	Source-drain current(Body Diode)	T <sub>c</sub> =25°C	--	--	-55	A
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =-25A, V <sub>GS</sub> =0V	--	0.86	-1.3	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>sd</sub> =-10A, V <sub>GS</sub> =0V	--	65	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=-100A/μs		125		nC

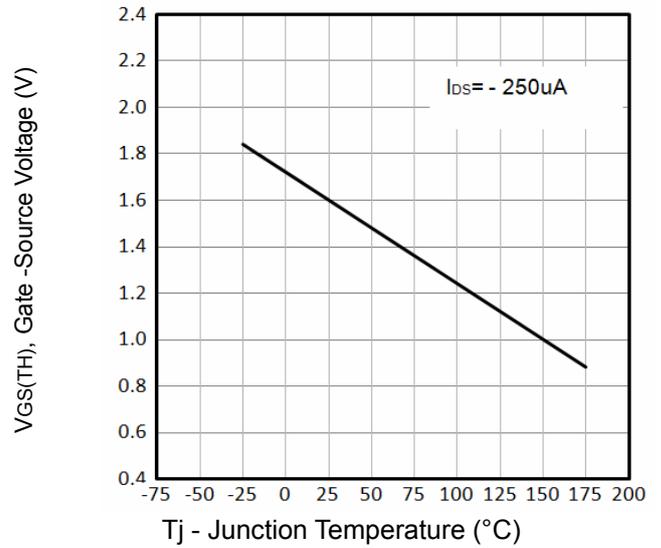
**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = -15A, V<sub>GS</sub> = -10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

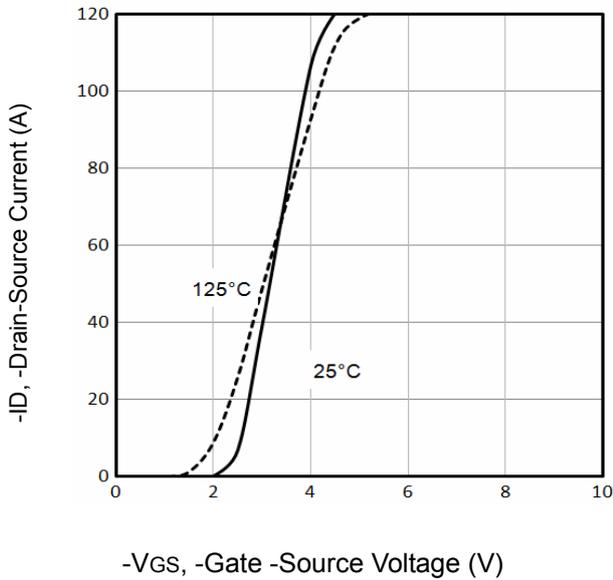
**Typical Characteristics**



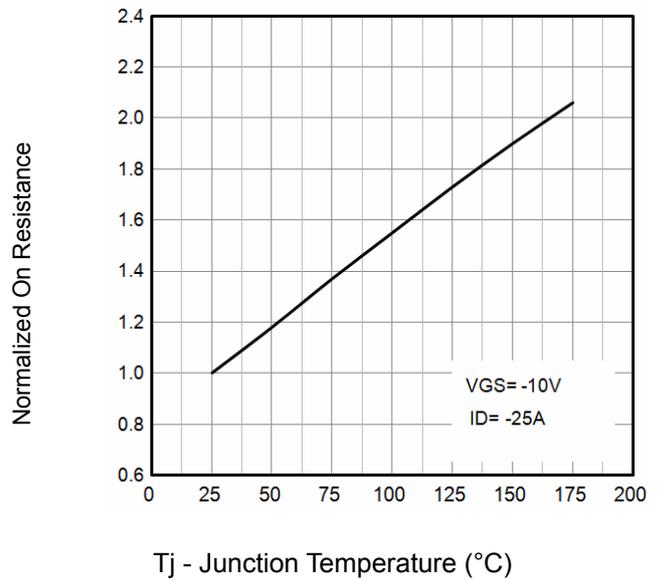
**Fig1.** Typical Output Characteristics



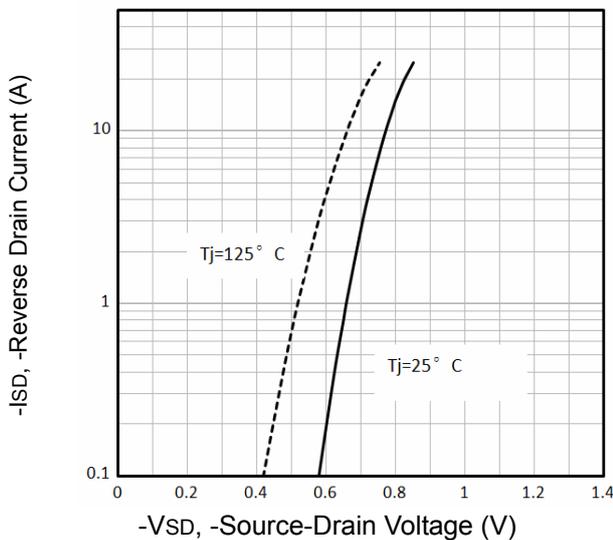
**Fig2.** Threshold Voltage Vs. Temperature



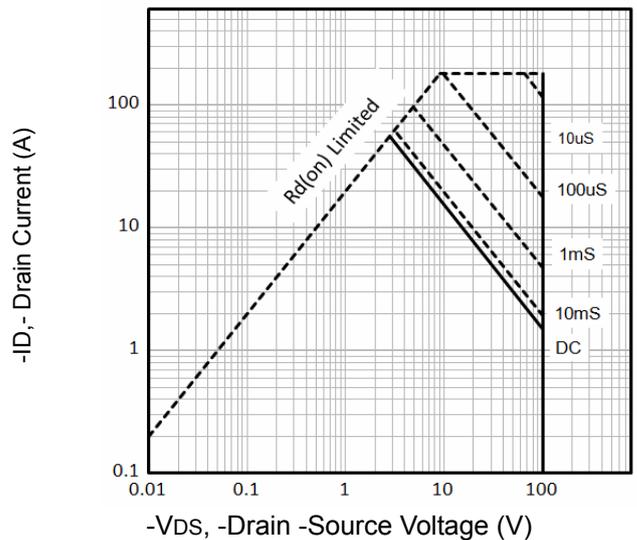
**Fig3.** Typical Transfer Characteristics



**Fig4.** Normalized On-Resistance Vs. Temperature

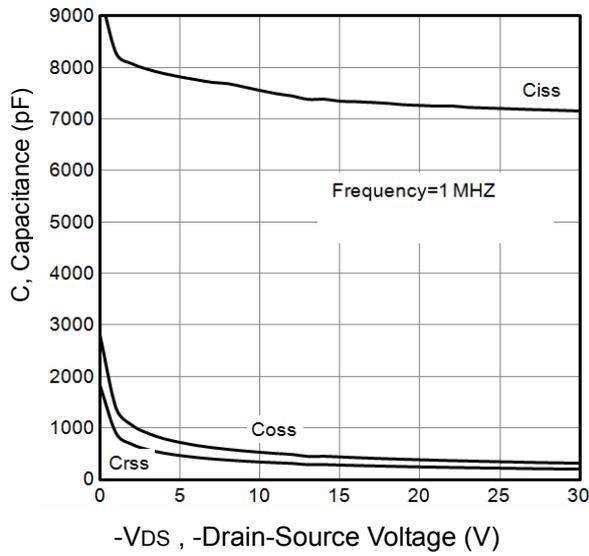


**Fig5.** Typical Source-Drain Diode Forward Voltage

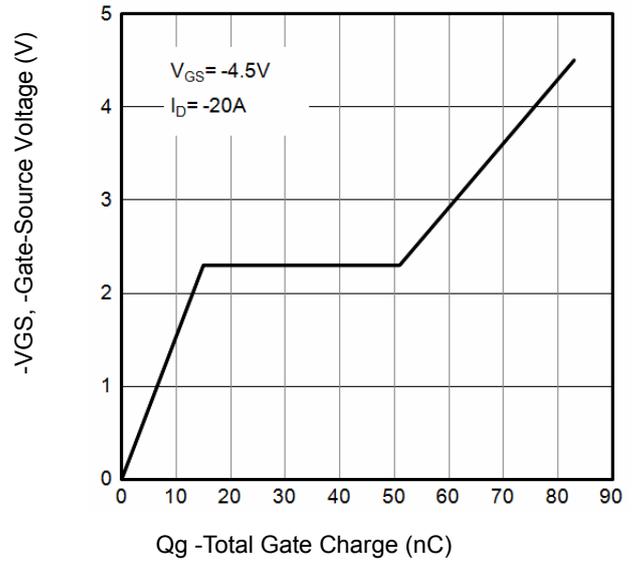


**Fig6.** Maximum Safe Operating Area

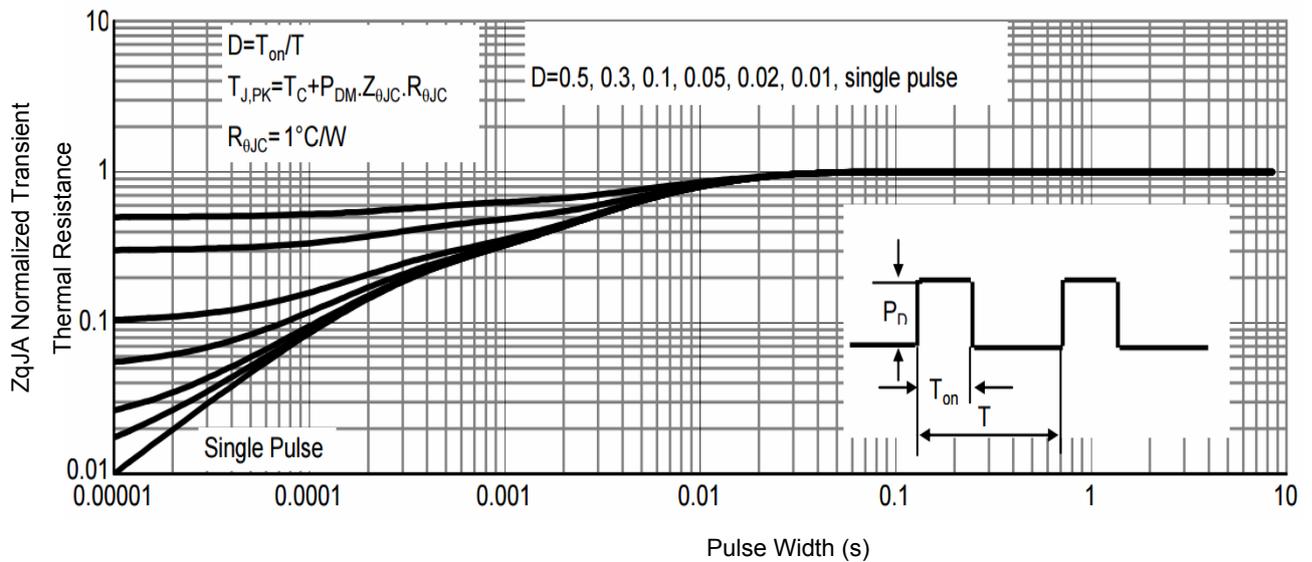
**Typical Characteristics**



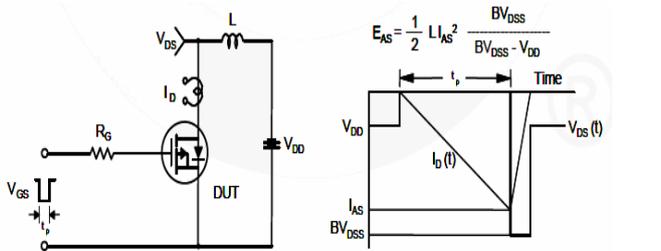
**Fig7.** Typical Capacitance Vs. Drain-Source Voltage



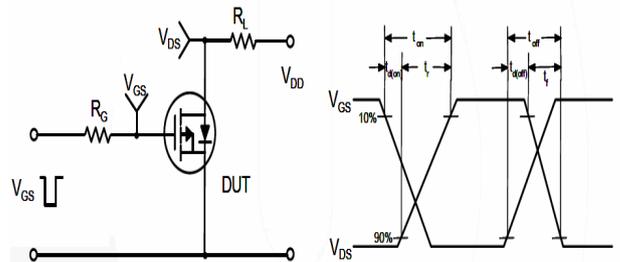
**Fig8.** Typical Gate Charge Vs. Gate-Source Voltage



**Fig9.** Normalized Maximum Transient Thermal Impedance

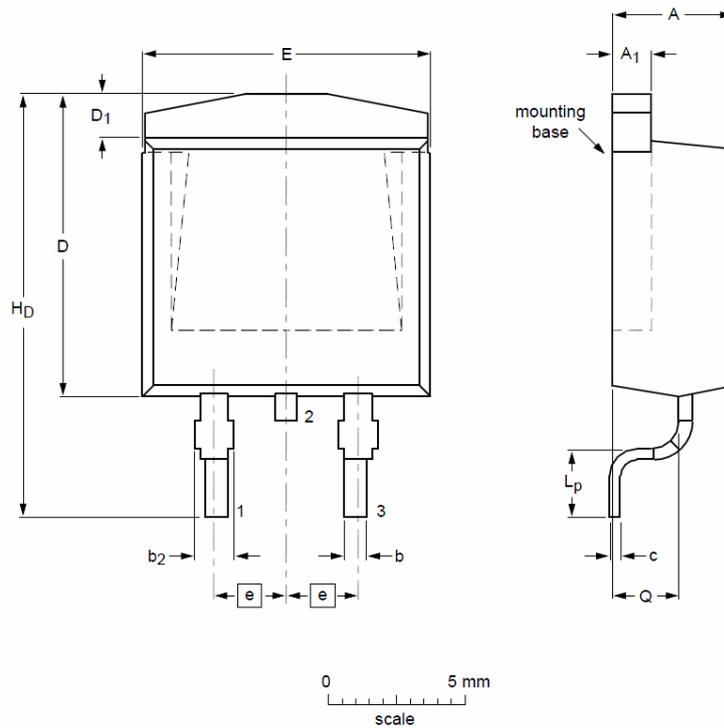


**Fig10.** Unclamped Inductive Test Circuit and Waveforms



**Fig11.** Switching Time Test Circuit and waveforms

**TO-263 Package Outline Data**



**DIMENSIONS** ( unit : mm )

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	4.40	4.55	4.70	A <sub>1</sub>	1.25	1.30	1.40
b	0.60	0.76	0.85	b <sub>2</sub>	1.05	1.30	1.45
c	0.35	0.45	0.60	D	9.80	10.20	10.50
D <sub>1</sub>	1.20	1.51	1.60	E	9.70	10.10	10.30
e	--	2.54	--	H <sub>D</sub>	14.80	15.45	15.80
L <sub>P</sub>	2.10	2.40	2.90	Q	2.20	2.50	2.60

**Customer Service**

Sales and Service:

[sales@vgsemi.com](mailto:sales@vgsemi.com)

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: [www.vgsemi.com](http://www.vgsemi.com)